

IN THE CLAIMS:

Claims 1-18 have been amended. All of the pending claims 1 through 18 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

1. (Currently Amended) A method for fabricating at least one emission structure, comprising:
forming at least one conductive structure extending across at least a portion of a substrate;
substantially removing a longitudinal portion of ~~said~~ the at least one conductive structure to
define at least one conductive layer substantially perpendicular to ~~said~~ the substrate, ~~said~~
the substrate being exposed along a length of ~~said~~ the at least one conductive layer; and
forming at least one emission structure adjacent ~~said~~ the at least one conductive layer.
2. (Currently Amended) The method of claim 1, wherein ~~said~~ forming ~~said~~ the at least one emission structure includes forming an emitter tip.
3. (Currently Amended) The method of claim 2, wherein ~~said~~ forming ~~said~~ the at least one emission structure further includes forming a resistor corresponding to ~~said~~ the at least one emitter tip.
4. (Currently Amended) The method of claim 3, wherein ~~said~~ forming ~~said~~ the resistor comprises forming ~~said~~ the resistor adjacent to ~~said~~ the at least one conductive layer.
5. (Currently Amended) The method of claim 1, wherein ~~said~~ forming ~~said~~ the at least one emission structure comprises forming a plurality of lines of emission structures.
6. (Currently Amended) The method of claim 5, wherein ~~said~~ substantially removing comprises electrically isolating at least one emission structure located along a first line

of ~~said~~ the plurality of lines from at least one emission structure located along an adjacent, second line of ~~said~~ the plurality of lines.

7. (Currently Amended) The method of claim 1, wherein ~~said~~ forming ~~said~~ the at least one conductive structure comprises:
disposing a layer comprising conductive material over ~~said~~ the substrate; and
patterning ~~said~~ the layer.

8. (Currently Amended) The method of claim 1, wherein ~~said~~ forming ~~said~~ the at least one emission structure comprises forming ~~said~~ the at least one emission structure from at least one of semiconductive material and conductive material.

9. (Currently Amended) The method of claim 1, wherein ~~said~~ forming ~~said~~ the at least one emission structure comprises forming ~~said~~ the at least one emission structure so as to extend over a lateral edge of ~~said~~ the at least one conductive structure.

10. (Currently Amended) A method for fabricating at least one emission structure, comprising:
forming at least one conductive structure that extends at least partially across a substrate;
forming at least one emitter tip and a corresponding resistor adjacent to ~~said~~ the at least one conductive structure; and
substantially removing at least a longitudinal portion of ~~said~~ the at least one conductive structure along substantially an entire length thereof to define at least one conductive layer substantially perpendicular to ~~said~~ the substrate.

11. (Currently Amended) The method of claim 10, wherein ~~said~~ forming ~~said~~ the at least one conductive structure comprises:

disposing a layer comprising conductive material on ~~said~~ the substrate; and patterning ~~said~~ the layer.

12. (Currently Amended) The method of claim 10, wherein ~~said~~ forming ~~said~~ the at least one emitter tip comprises forming ~~said~~ the at least one emitter tip from at least one of semiconductive material and conductive material.

13. (Currently Amended) The method of claim 10, wherein ~~said~~ forming ~~said~~ the corresponding resistor comprises forming ~~said~~ the corresponding resistor from at least one of semiconductive material and conductive material.

14. (Currently Amended) The method of claim 10, wherein ~~said~~ forming ~~said~~ the at least one emitter tip comprises:
disposing at least one layer comprising at least one of semiconductive material and conductive material over ~~said~~ the substrate and ~~said~~ the at least one conductive structure;
removing a longitudinal portion of at least one region of ~~said~~ the at least one layer located over ~~said~~ the at least one conductive structure to expose at least a substantially longitudinal portion of ~~said~~ the at least one conductive structure; and
patterning at least one remaining portion of ~~said~~ the at least one layer.

15. (Currently Amended) The method of claim 14, wherein ~~said~~ patterning ~~said~~ the at least one remaining portion of ~~said~~ the at least one layer includes defining ~~said~~ the at least one emitter tip from ~~said~~ the at least one layer.

16. (Currently Amended) The method of claim 15, wherein ~~said~~ patterning ~~said~~ the at least one remaining portion of ~~said~~ the at least one layer further includes forming ~~said~~ the corresponding resistor.

17. (Currently Amended) The method of claim 10, wherein ~~said~~ substantially removing comprises leaving at least a lateral edge of ~~said~~ the at least one conductive structure along substantially ~~said~~ the entire length thereof.

18. (Currently Amended) The method of claim 10, wherein ~~said~~ forming ~~said~~ the at least one emitter tip comprises forming ~~said~~ the at least one emitter tip so as to extend over a lateral edge of ~~said~~ the at least one conductive structure.